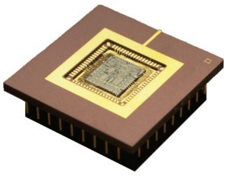
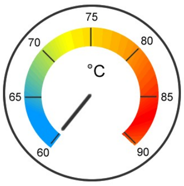
MOLYDUVAL
Wapa FE 3





Silicone Free Heat Sink Compound

Non Silicone Heat Sink compound designed to eliminate the potential problems of silicone based compounds, caused by migration and component contamination. This compound uses a special synthetic base, fortified with metal oxides and compounded to a paste-like consistency for ease of application.

Its highly efficient thermal conductive properties mean a more rapid transfer of heat for longer component life. The high temperature stability provides physical properties of low bleed and evaporation for long term service in many applications. Will not harden, melt or migrate.

The use of synthetic ester fluids and metal oxide fillers provides excellent conductive properties. The product is compatible with many metal and plastic components used in the fabrication of electronic devices. The high temperature stability and of this compound mean a longer and more efficient life for all types of hardware designs.

Characteristics

- high temperature resistance
- insensitive against humidity
- chemically inert
- chemically inert to most materials like plastic and rubber
- silicone free, no dirtying on solder bands
- good corrosion protection even with aluminium and magnesium alloys
- does not melt
- will not harden
- non toxic
- low oil bleeding

Applications

- for metal and plastic semiconductors
- for transistors, diodes, and similar components

Technical Datas

Color		white
Base Fluid		polyol ester
Thickener		anorganic
Name		ISO-L-XDGEA2,5
Name		MF2,5
Consistency Class NLGI		2-3
Viscosity Base Fluid, 100°C	mm²/s	150
Temperature Range	°C	-40 -> +200
Dropping Point	°C	no
Pack Size tube 100 g		+

The indicated service temperatures are guide values depending on the lubricants composition and on the application. They may vary in case of special influences or ongoing use.

For further information, please see our website https://www.solano-industries.com/en/